



INDIAN INSTITUTE OF TECHNOLOGY BOMBAY

MATERIALS MANAGEMENT DIVISION

Powai, Mumbai 400076.

Ref. : Rfx-6100002500

PR No.1000050108

Item Description: Wire Bonder

Sr. No	Item Description	Detailed Technical Specification	Technical Compliance (Yes / No)	Additional Information (if any)
1.	Wire Bonder	Wire Bonder Compatible with thin-wire, heavy-wire and ribbon bonding (either through separate machines or a single machine with multiple bondheads) Thin-wire bonding of Al wire with diameter: 17 to 75 micron Heavy-wire bonding of Al wire with diameter: 100 to 500 micron Heavy-wire bonding of Cu wire with diameter: 100 to 300 micron Ribbon bonding of Al ribbon of size: 300 x 1500 micron Supporting equipment and consumables (bonding wedges, PC, wire, ribbon) Warranty: 12 months Delivery period: 20-22 weeks		